

**AMENDMENTS TO THE CLAIMS**

1. to 7. previously canceled

8. (previously added) A composition comprising the product obtained by blending to homogeneity:

(A) 100 parts by weight of a polyorganosiloxane containing at least two alkenyl radicals per molecule;

(B) an organohydrogensiloxane containing at least two silicon-bonded hydrogen atoms in each molecule, in a quantity sufficient to provide from 0.5 to 3 silicon-bonded hydrogen atoms per alkenyl radical in ingredient (A);

B<sup>1</sup>  
(C) from 50 to 2,000 parts by weight of finely divided silver particles pre-treated with an organosilicon compound selected from the group consisting of (i) silanes containing at least one alkoxy group and (ii) organosiloxanes;

(D) an amount sufficient to promote curing of said composition of a platinum catalyst;

(E) up to 20 weight percent, based on the weight of component (A), of ingredient (E), an organosilicon compound containing at least one silicon-bonded alkoxy group per molecule; and

(F) 0.001 to 5 weight parts, per 100 weight parts of ingredient (A), of a cure inhibitor.

9. (previously added) The composition of claim 8, where ingredient (C)(i) comprises an alkoxysilane comprising:

- (a) methyltrimethoxysilane,
- (b) vinyltrimethoxysilane,
- (c) 3-glycidoxypropyltrimethoxysilane,

- (d) 3-methacryloxypropyltrimethoxysilane,
- (e) dimethyldimethoxysilane,
- (f) trimethylmethoxysilane,
- (g) trimethylethoxysilane,
- (h) tetramethoxysilane, and
- (i) tetraethoxysilane.

10. (currently amended) The composition of claim 8, where ingredient (C)(ii) comprises

- (a) a siloxane oligomer,
- (b) a linear polyorganosiloxane,
- (c) a cyclosiloxane,
- (d) a ~~siloxane~~-silicone resin, or
- (e) a mixture thereof.

11. (previously added) The composition of claim 8, where ingredient (C)(ii) comprises a siloxane oligomer comprising:

- (a) a silanol endblocked dimethylsiloxane oligomer,
- (b) a silanol endblocked dimethylsiloxane/methylvinylsiloxane co-oligomer,
- (c) a silanol endblocked methylvinylsiloxane oligomer, or
- (d) a silanol endblocked methylphenylsiloxane oligomer.

12. (previously added) The composition of claim 8, where ingredient (C)(ii) comprises a linear polyorganosiloxane comprising:

- (a) a trimethylsiloxy endblocked polydimethylsiloxane,
- (b) a trimethylsiloxy endblocked dimethylsiloxane/ methylvinylsiloxane copolymer,
- (c) a trimethylsiloxy endblocked dimethylsiloxane/ methylphenylsiloxane copolymer,
- (d) a trimethylsiloxy endblocked polymethylhydrogensiloxane,
- (e) a trimethylsiloxy endblocked dimethylsiloxane/ methylhydrogen siloxane copolymer,
- (f) a silanol endblocked polydimethylsiloxane,

- (g) a silanol endblocked dimethylsiloxane/ methylvinylsiloxane copolymer,  
(h) a silanol endblocked dimethylsiloxane/ methylphenylsiloxane copolymer,  
(i) a silanol endblocked polydimethylhydrogensiloxane,  
(j) a silanol endblocked dimethylsiloxane/ methylhydrogensiloxane copolymer,  
(k) a dimethylvinylsiloxyl endblocked polydimethylsiloxane,  
(l) a dimethylvinylsiloxyl endblocked dimethylsiloxane/ methylvinylsiloxane copolymer,  
(m) a dimethylvinylsiloxyl endblocked dimethylsiloxane/ methylphenylsiloxane  
copolymer,  
(n) a dimethylhydrogensiloxyl endblocked polymethylhydrogensiloxane, or  
(o) a dimethylhydrogensiloxyl endblocked dimethylsiloxane/ methylhydrogensiloxane  
copolymer.

B' 13. (previously added) The composition of claim 8, where ingredient (C)(ii) comprises a cyclosiloxane comprising 1,3,5,7-tetramethylcyclotetrasiloxane or 1,3,5,7,9-pentamethylcyclopentasiloxane.

14. (previously added) The composition of claim 8, where ingredient (C)(ii) comprises a silicone resin comprising:

- (a) a resin comprising  $R_3SiO_{1/2}$  and  $SiO_{4/2}$  units,  
(b) a resin comprising  $RSiO_{3/2}$  units,  
(c) a resin comprising  $R_2SiO_{2/2}$  and  $RSiO_{3/2}$  units, or  
(d) a resin comprising  $R_2SiO_{2/2}$ ,  $RSiO_{3/2}$ , and  $SiO_{4/2}$  units,

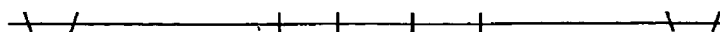
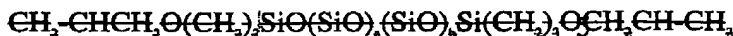
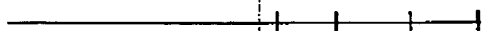
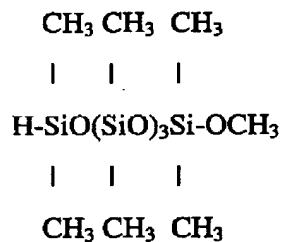
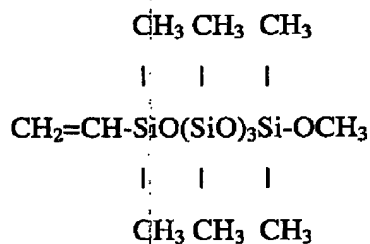
where each R represents a substituted or unsubstituted monovalent hydrocarbon.

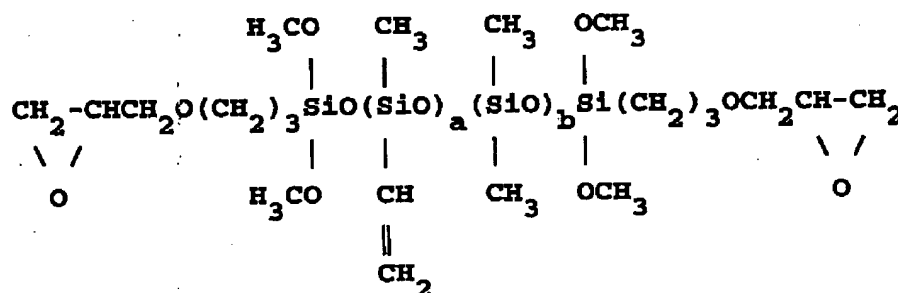
15. (previously added) The composition of claim 8, where the composition contains 0.5 to 8 parts by weight of ingredient (E), per 100 parts by weight of ingredient (A), and ingredient (E) further comprises at least one substituent selected from the group consisting of silicon bonded hydrogen, silicon-bonded vinyl, epoxy and trialkoxysilylalkyl radicals.

16. (previously added) The composition of claim 8, where ingredient (E) comprises an alkoxysilane comprising:

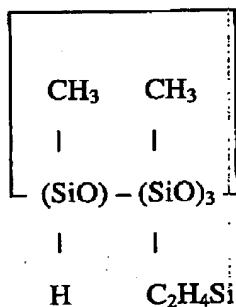
- (i) tetramethoxysilane,  
 (ii) tetraethoxysilane,  
 (iii) dimethyldimethoxysilane,  
 (iv) methylphenyldimethoxysilane,  
 (v) methylphenyldiethoxysilane,  
 (vi) phenyltrimethoxysilane,  
 (vii) methyltrimethoxysilane,  
 (viii) methyltriethoxysilane,  
 (ix) vinyltrimethoxysilane,  
 (x) allyltrimethoxysilane,  
 (xi) allyltriethoxysilane,  
 (xii) 3-glycidoxypropyltrimethoxysilane, or  
 (xiii) 3-methacryloxypropyltrimethoxysilane.

17. (currently amended) The composition of claim 8, where ingredient (E) comprises an organosilicon compound comprising:

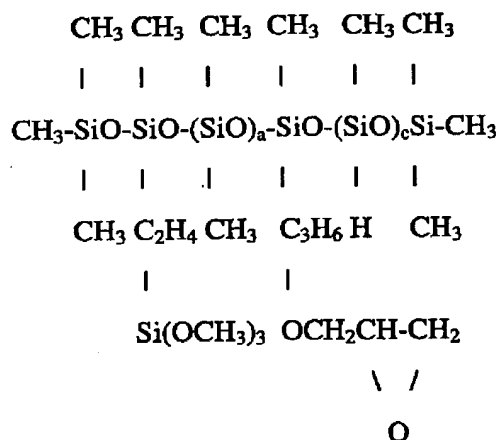




where a and b are each integers with values of at least 1.



, or



18. (previously added) The composition of claim 8, where ingredient (F) comprises an alkynyl alcohol, an ene-yne compound, 1,3,5,7-tetramethyl-1,3,5,7-tetravinylcyclotetrasiloxane, 1,3,5,7-tetramethyl-1,3,5,7-tetrahexenylcyclotetrasiloxane, or benzotriazole.

B<sup>1</sup>  
19. (previously added) The composition of claim 8, where ingredient (B) has at least one silicon-bonded alkoxy group per molecule and ingredient (E) has not more than one silicon-bonded hydrogen atom per molecule.

20. (previously added) The composition of claim 8 when cured on a solid substrate.

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